0.5µA I_Q, 300mA Linear Regulator

General Description

The EHP8150 features of low quiescent current as low as 0.5µA and almost zero disable current which is ideal for powering the battery equipment to a longer service life. The EHP8150 guarantees delivery of 300mA output current and can be stable with 1µF ceramic output capacitor.

The EHP8150 is available in SOT23-3, SOT23-5 and uDFN1X1-4 surface mount packages.

Applications

- Portable, Battery Powered Equipment
- Ultra Low Power Microcontroller
- Notebook computers

Features

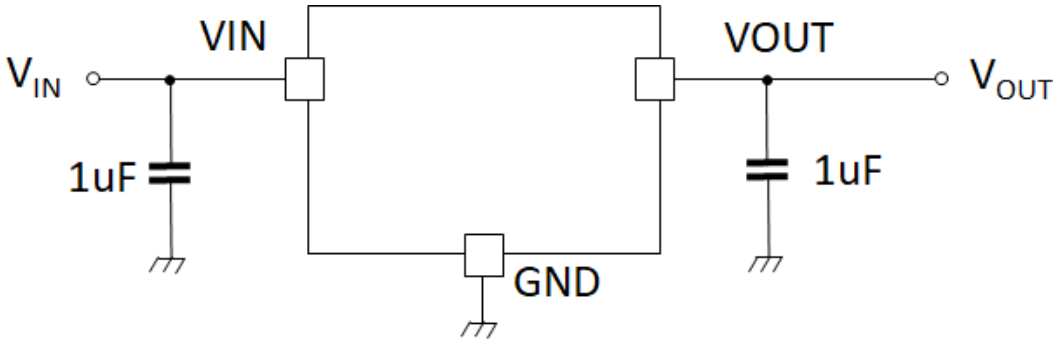
- 2.5V to 5.5V input range
- 300mA output current driving capacity
- 0.5µA typical quiescent current at no Load
- 400mV typical dropout at I_{OUT} = 300mA
- Thermal shutdown protection
- Internal short-circuit current l imit
- Stable with 1µF output capacitor

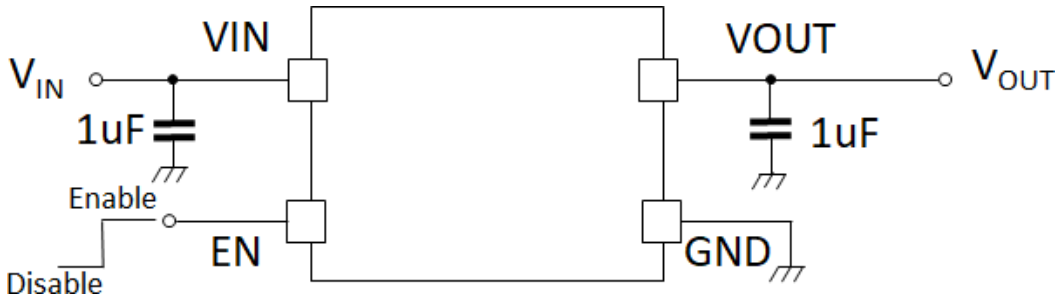
Ordering Information

Part Number	Remark
EHP8150-XXVD03NRR	±2% output voltage tolerance
EHP8150-XXVF05NRR	±2% output voltage tolerance
EHP8150-XXDC04NRR	±2% output voltage tolerance

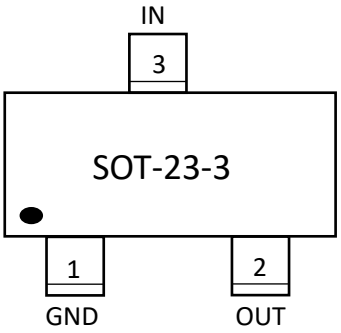
XX:12=1.2V, 15=1.5V, 18=1.8V, 25=2.5V, 30=3.0V, 33=3.3V

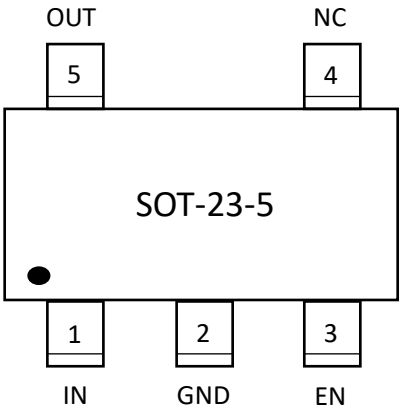
Typical Application

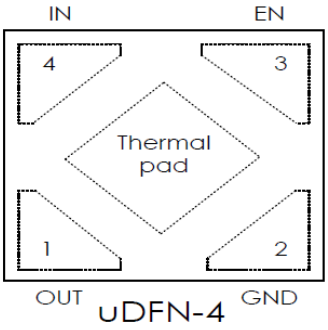




Connection Diagrams







Order information

EHP8150-XXVD03NRR

XX	Output voltage
VD03	SOT-23-3 Package
NRR	RoHS & Halogen free package Rating: -40 to 85°C Package in Tape & Reel

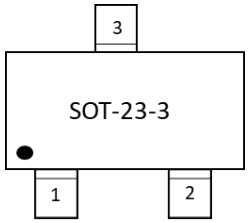
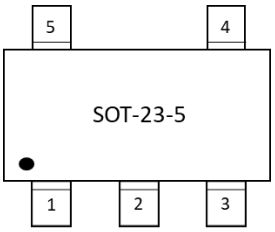
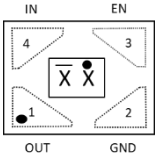
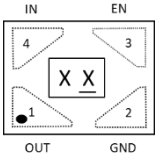
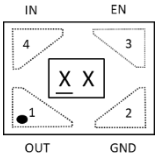
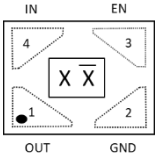
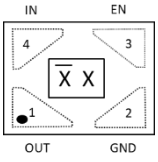
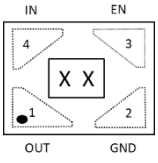
EHP8150-XXVF05NRR

XX	Output voltage
VF05	SOT-23-5 Package
NRR	RoHS & Halogen free package Rating: -40 to 85°C Package in Tape & Reel

EHP8150-XXDC04NRR

XX	Output voltage
DC04	uDFN1x1-4 Package
NRR	RoHS & Halogen free package Rating: -40 to 85°C Package in Tape & Reel

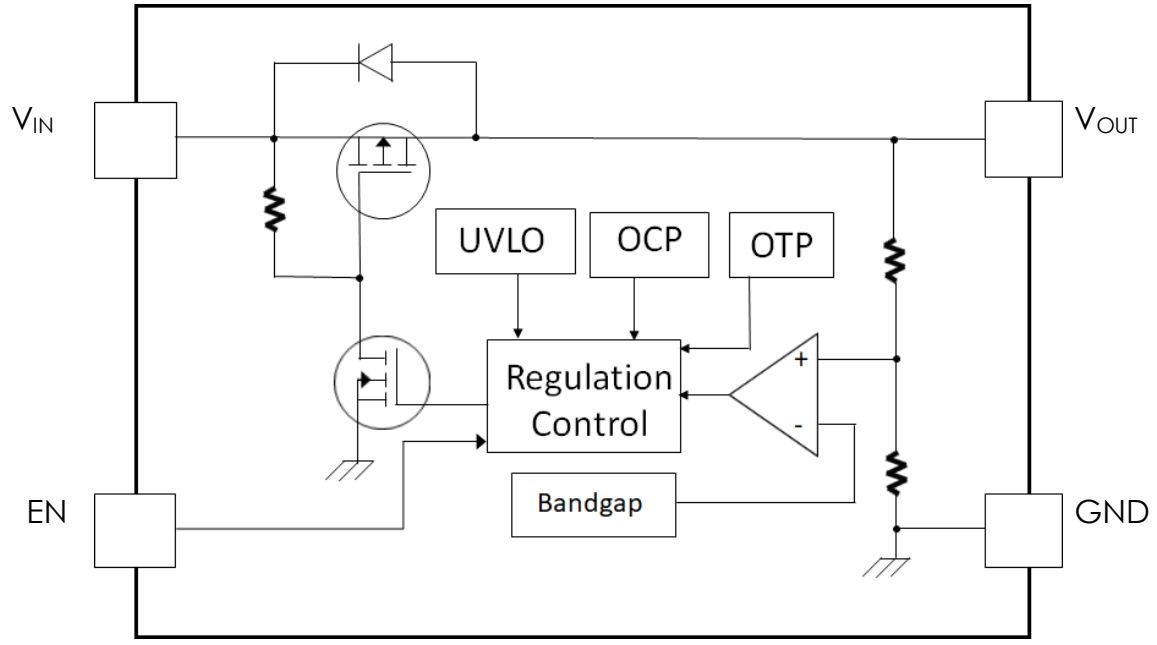
Order, Marking and Packing Information

Package	Vout	Product ID.	Marking		Packing
SOT-23-3	1.2V	EHP8150-12VD03NRR			Tape & Reel 3K pcs
	1.5V	EHP8150-15VD03NRR			
	1.8V	EHP8150-18VD03NRR			
	2.5V	EHP8150-25VD03NRR			
	3.0V	EHP8150-30VD03NRR			
	3.3V	EHP8150-33VD03NRR			
SOT-23-5	1.2V	EHP8150-12VF05NRR			Tape & Reel 3K pcs
	1.5V	EHP8150-15VF05NRR			
	1.8V	EHP8150-18VF05NRR			
	2.5V	EHP8150-25VF05NRR			
	3.0V	EHP8150-30VF05NRR			
	3.3V	EHP8150-33VF05NRR			
DFN1x1-4	1.2V	EHP8150-12DC04NRR		XX=tracking code	Tape & Reel 8K pcs
	1.5V	EHP8150-15DC04NRR			
	1.8V	EHP8150-18DC04NRR			
	2.5V	EHP8150-25DC04NRR			
	3.0V	EHP8150-30DC04NRR			
	3.3V	EHP8150-33DC04NRR			

Pin Functions

Name	SOT-23-3	SOT-23-5	uDFN1x1-4	Function
V_{IN}	3	1	4	Supply Voltage Input Require a minimum input capacitor of close to 1μF to ensure stability and sufficient decoupling from the ground pin.
GND	1	2	2	Ground Pin
EN	N/A	3	3	Enable Input. Enable the regulator by pulling the EN pin High. To keep the regulator on during normal operation, connect the EN pin to VIN. The EN pin must not exceed VIN under all operating conditions.
NC	N/A	4	N/A	No connection
V_{OUT}	2	5	1	Regulated Output Voltage Pin. A small 1μF ceramic capacitor is needed from this pin to ground to assure stability
Thermal Pad	N/A	N/A	YES	The thermal pad with large thermal land area on the PCB will helpful chip power dissipation, to connect it to GND together normally.

Functional Block Diagram



Functional Block Diagram of EHP8150

Absolute Maximum Ratings (Note1, 2)

V_{IN}, EN	-0.3V to 6V	Junction Temperature (T_J)	125°C
Storage Temperature Range	-65°C to 150°C	Lead Temperature (Soldering, 10 sec.)	260°C
		ESD Rating	
		Human Body Model	2KV

Recommended Operating Conditions (Note1, 2)

Supply Voltage	2.5V to 5.5V	Operating Temperature Range	-40°C to 85°C

Thermal Resistance:

Symbol	θ_{JA}(Note3)	θ_{JC}(Note4)
SOT23-3	250(℃/W)	81(℃/W)
SOT23-5	152(℃/W)	81(℃/W)
uDFN1x1-4	110(℃/W)	23(℃/W)

Electrical Characteristics

Unless otherwise specified, all limits guaranteed for V_{IN}=V_{EN} =V_{OUT}+1V, C_{IN}=C_{OUT}=1uF, T_a = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Output Voltage Accuracy	$\triangle V_{OUT}$		-2%		2%	V
Line Regulation	$\triangle V_{LINE}$	V_{IN}=V_{OUT} + 1V to 5.5V,		20	50	mV
Load Regulation	$\triangle V_{LOAD}$	I_{OUT}= 1mA to 150mA		12	30	mV
		I_{OUT}= 1mA to 300mA		25	60	
Dropout Voltage	V_{DROP}	I_{OUT}=100mA		130		mV
		I_{OUT}=300mA		400		mV
Quiescent Current	I_Q	T_J= 25℃		0.5	1	uA
Current Limit	I_{CL}		360	560		mA
Enable high level	V_{ENHI}		0.6			V
Enable low level	V_{ENLO}				0.2	V
Thermal Shutdown	TSD			150		℃
Thermal ShutdownHysteresis	THY			20		℃
Power-supply rejection ratio	PSRR	f = 1kHz		60		dB

Note 1: Absolute Maximum ratings indicate limits beyond which damage may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions.

Note 2: All voltages are with respect to the potential at the ground pin.

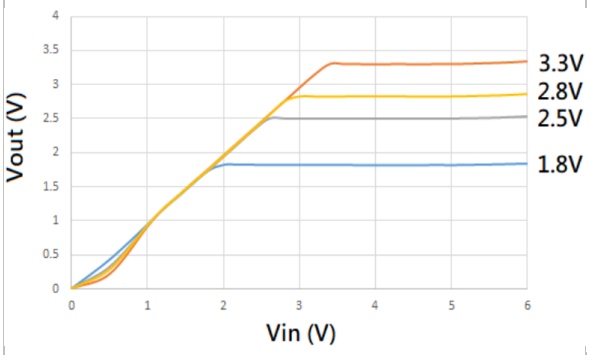
Note 3: θ_{JA} is measured in the natural convection at TJ=25℃ on a high effective thermal conductivity test board (2 layers, 2S0P).

Note 4: θ_{JC} represents the resistance to the heat flows the chip to package top case.

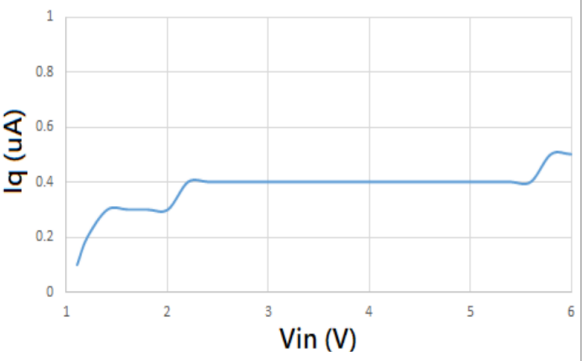
Typical Performance Characteristics

V_{IN}=12V, I_{OUT}=1mA, V_{OUT}=3.3V, C_{IN}=C_{OUT}=1uF, T_a=25°C, unless otherwise specified

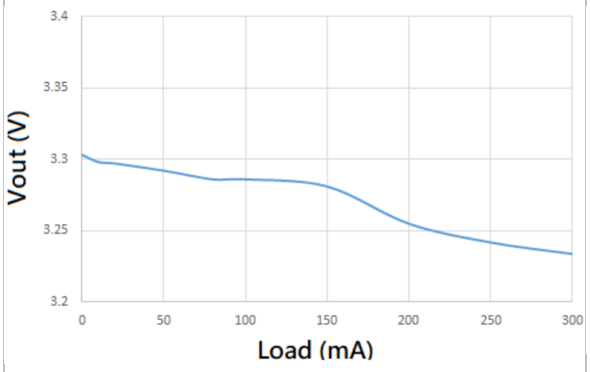
V_{OUT} vs V_{IN}(I_{OUT}=1mA)



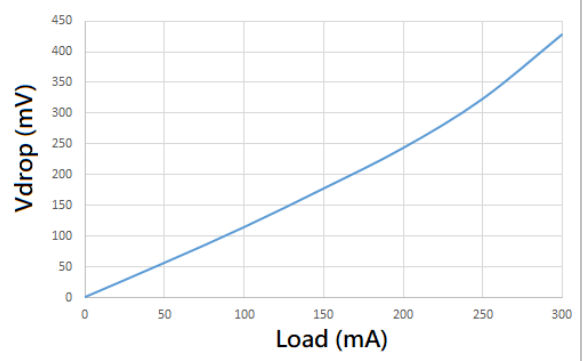
I_Q vs V_{IN}(I_{OUT}=0mA)



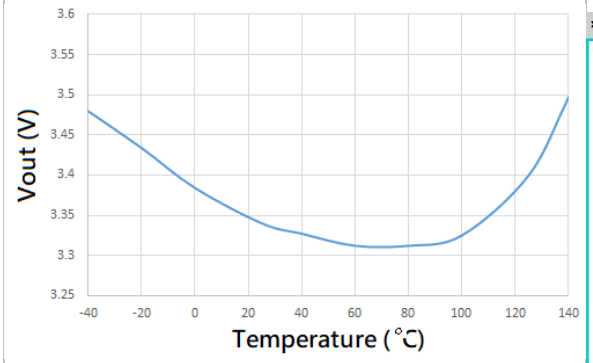
V_{OUT} vs Load



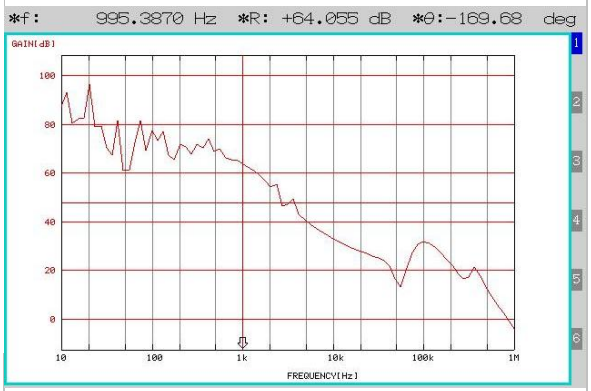
Dropout vs Load



V_{OUT} (3.3V) vs Temperature



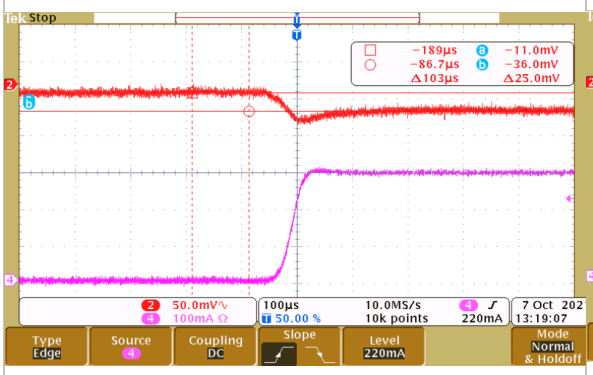
PSRR vs Frequency (V_{IN} = 4.8V, V_{OUT} = 1.8V)



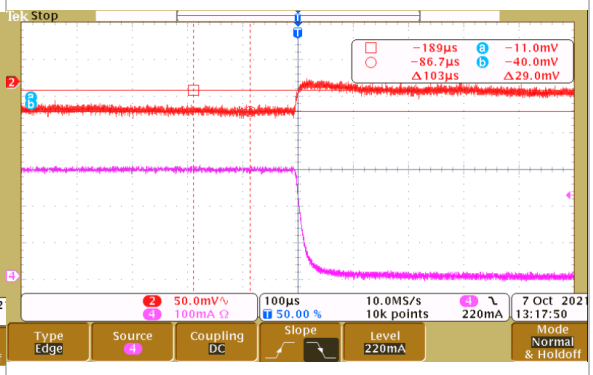
Typical Performance Characteristics (cont.)

V_{IN}=12V, I_{OUT}=1mA, V_{OUT}=3.3V, C_{IN}=C_{OUT}=1uF, T_a=25°C, unless otherwise specified

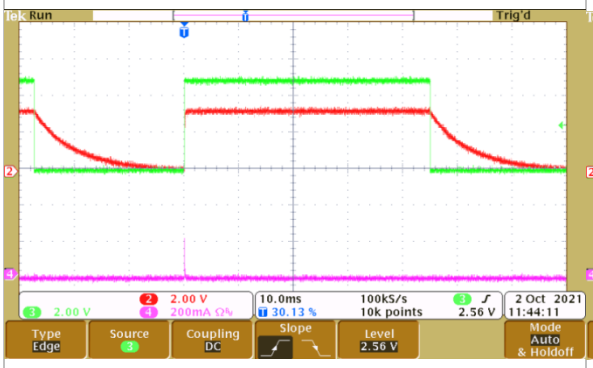
V_{OUT} Load Transient (1 to 300mA)



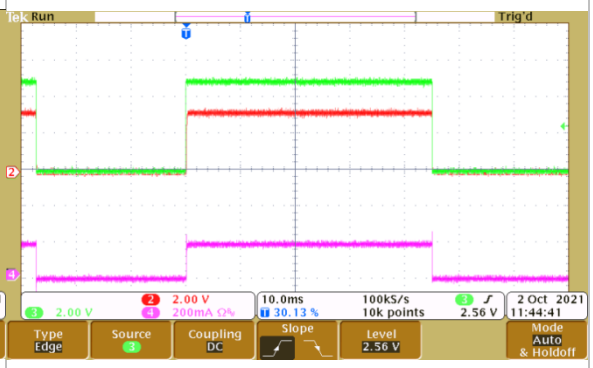
V_{OUT} Load Transient (300 to 1mA)



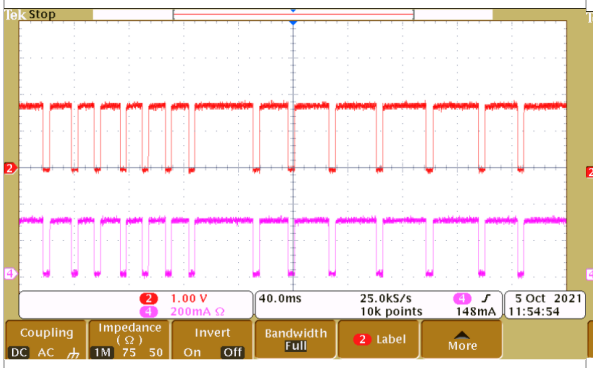
Enable Startup (no load)



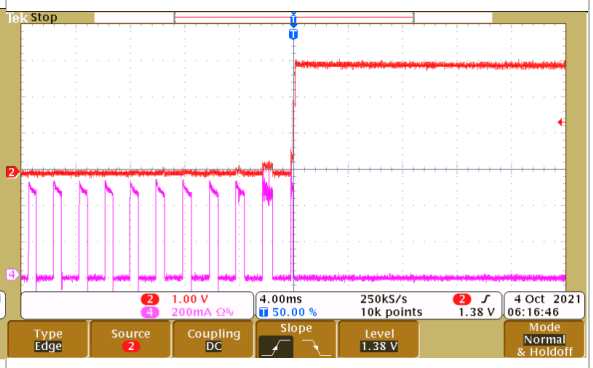
Enable Startup(200mA load)



VIN = 5V, VOUT = 1.8V, heavy load OTP



V_{OUT} short to GND and release



Application Information

Output Capacitor

The EHP8150 is specially designed for use with ceramic output capacitors of as low as 1μF to take advantage of the savings in cost and space as well as the superior filtering of high frequency noise. Capacitors of higher value or other types may be used, but it is important to make sure its equivalent series resistance (ESR) is restricted to than 0.5Ω. The use of larger capacitors with smaller ESR values is desirable for applications involving large and fast input or output transients, as well as for situations where the application systems are not physically located immediately adjacent to the battery power source. Typical ceramic capacitors suitable for use with the EHP8150 are X5R and X7R. The X5R and the X7R capacitors are able to maintain their capacitance values to within ±20% and ±10%, respectively, as the temperature increases.

Input Capacitor

A minimum input capacitance of 1μF is required for EHP8150. The capacitor value may be increased without limit. Improper workbench set-ups may have adverse effects on the normal operation of the regulator. A case in point is the instability that may result from long supply lead inductance coupling to the output through the gate capacitance of the pass transistor. This will establish a pseudo LCR network, and is likely to happen under high current conditions or near dropout. A 10μF tantalum input capacitor will dampen the parasitic LCR action thanks to its high ESR. However, cautions should be exercised to avoid regulator short-circuit damage when tantalum capacitors are used, for they are prone to fail in short-circuit operating conditions.

Power Dissipation and Thermal Shutdown

Thermal overload results from excessive power dissipation that causes the IC junction temperature to increase beyond a safe operating level. The EHP8150 relies on dedicated thermal shutdown circuitry to limit its total power dissipation. An IC junction temperature T_J exceeding 150°C will trigger the thermal shutdown logic, turning off the P-channel MOS pass transistor. The pass transistor turns on again after the junction cools off by about 20°C. When continuous thermal overload conditions persist, this thermal shutdown action then results in a pulsed waveform at the output of the regulator. The concept of thermal resistance θ_{JA} (°C/W) is often used to describe an IC junction's relative readiness in allowing its thermal energy to dissipate to its ambient air. An IC junction with a low thermal resistance is preferred because it is relatively effective in dissipating its thermal energy to its ambient, thus resulting in a relatively low and desirable junction temperature. The relationship between θ_{JA} and T_J is as follows:

$$T_J = \theta_{JA} \times (P_D) + T_A$$

T_A is the ambient temperature, and P_D is the power generated by the IC and can be written as:

$$P_D = I_{OUT} (V_{IN} - V_{OUT})$$

As the above equations show, it is desirable to work with ICs whose θ_{JA} values are small such that T_J does not

increase strongly with P_D. To avoid thermally overloading the EHP8150, refrain from exceeding the absolute maximum junction temperature rating of 125°C under continuous operating conditions. Overstressing the regulator with high loading currents and elevated input-to-output differential voltages can increase the IC die temperature significantly.

Maximum power dissipation for the device is calculated using the following equation:

$$PD = \frac{\mathrm{TJ(max)} - \mathrm{TA}}{\mathrm{\Theta JA}}$$

Where TJ(MAX) is the maximum junction temperature, T_A is the ambient temperature, and Θ_{JA} is the junction-to-ambient thermal resistance. For example,

for the SOT-23-3 package Θ_{JA}=250°C/W, TJ(MAX)=125°C and using T_A=25°C, the maximum power dissipation is 0.4W.

for the SOT-23-5 package Θ_{JA}=152°C/W, TJ(MAX)=125°C and using T_A=25°C, the maximum power dissipation is 0.65W.

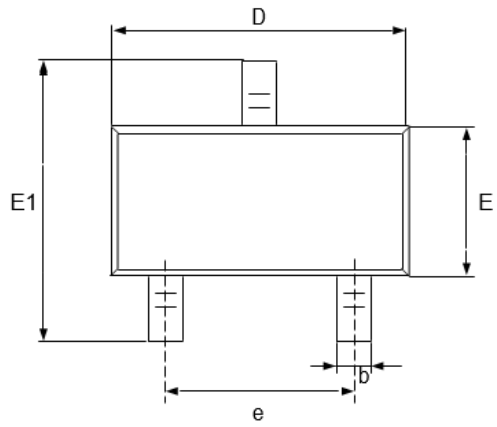
for the SOT-89-3 package Θ_{JA}=90°C/W, TJ(MAX)=125°C and using T_A=25°C, the maximum power dissipation is 1.1W.

Shutdown

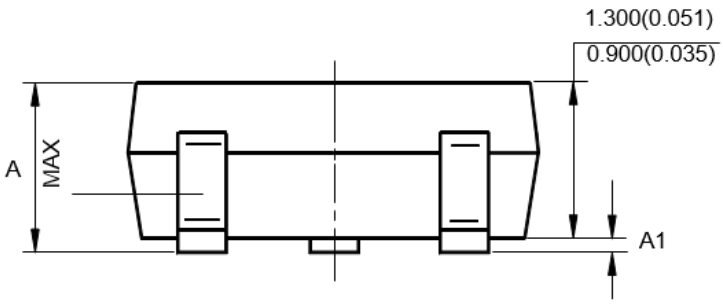
The EHP8150 enters the sleep mode when the EN pin is low. When this occurs, the pass transistor, the error amplifier, and the biasing circuits, including the bandgap reference, are turned off, thus reducing the supply current to typically 0.5μA. Such a low supply current makes the EHP8150 best suited for battery-powered applications. The maximum guaranteed voltage at the EN pin for the sleep mode to take effect is 0.2V.

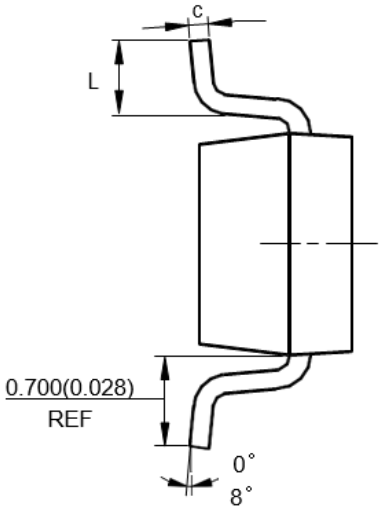
Package Outline Drawing

SOT-23-3



TOP VIEW



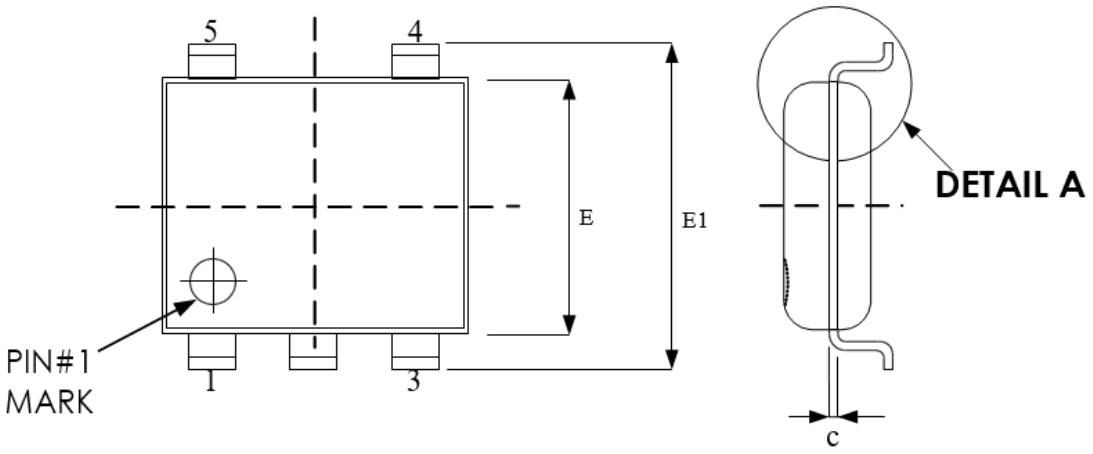


SIDE VIEW

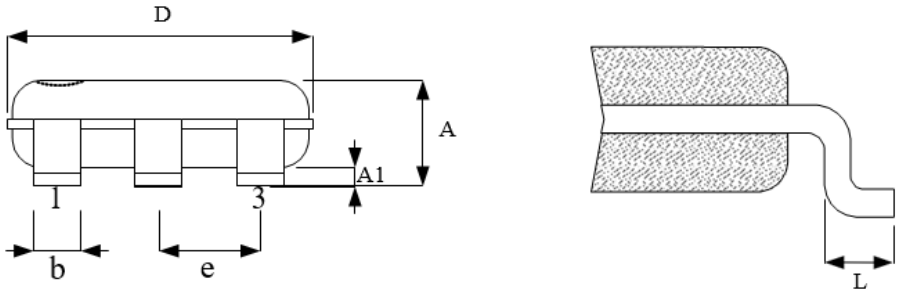
Symbol	Dimension in mm	
	Min.	Max.
A	0.90	1.45
A1	0.00	0.15
b	0.30	0.50
c	0.10	0.20
D	2.82	3.10
E	1.50	1.70
E1	2.65	3.00
e	1.80	2.00
L	0.30	0.60

Package Outline Drawing

SOT-23-5



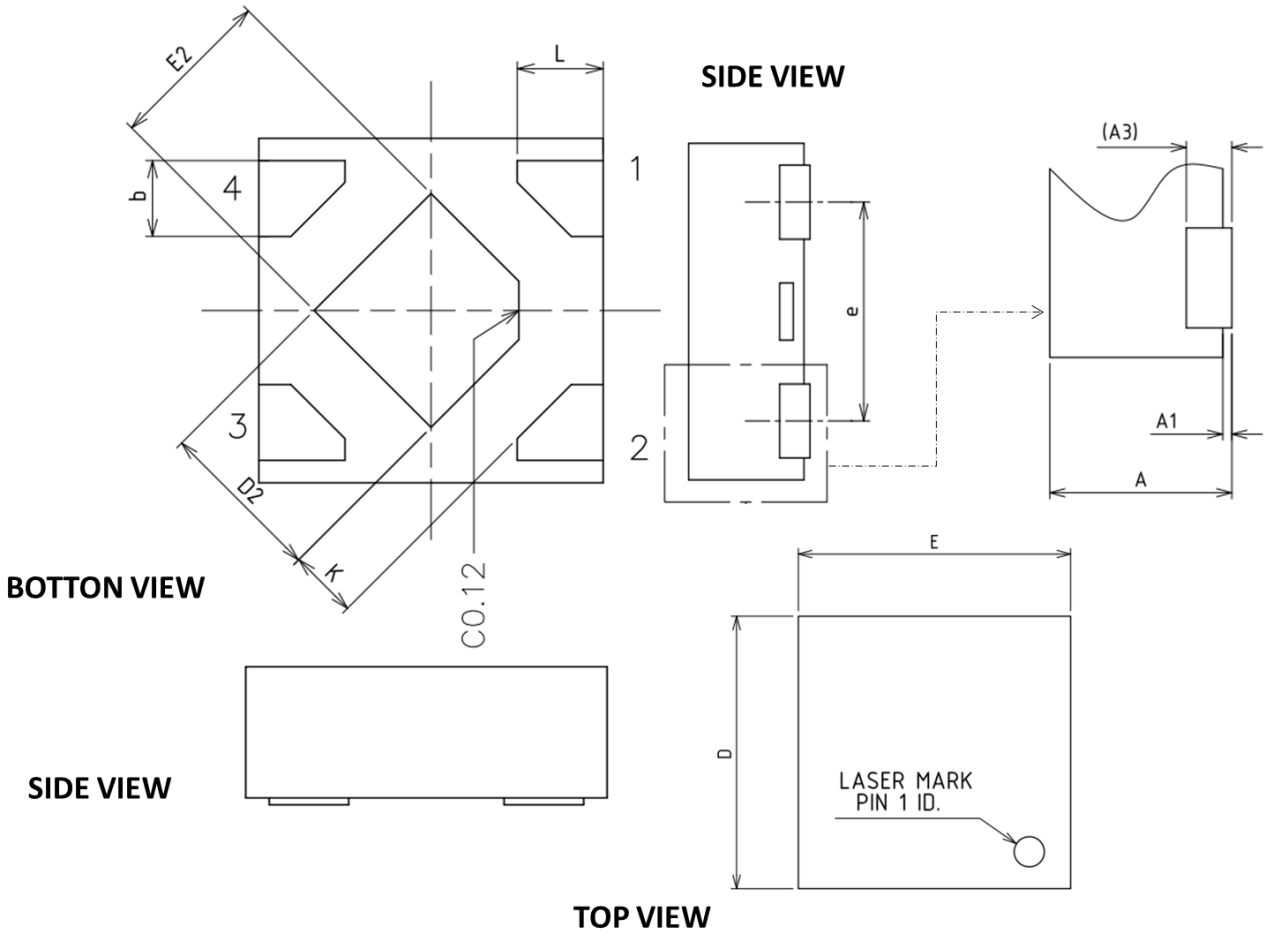
TOP VIEW



SIDE VIEW **DETAIL A**

Symbol	Dimension in mm	
	Min.	Max.
A	0.90	1.45
A1	0.00	0.15
b	0.30	0.50
c	0.08	0.25
D	2.70	3.10
E	1.40	1.80
E1	2.60	3.00
e	0.95 BSC	
L	0.30	0.60

Package Outline Drawing
uDFN-4L (1mm x 1mm)



Symbol	Dimension in mm		
	Min.	Typ.	Max.
A	0.34	0.37	0.40
A1	0.00	0.02	0.05
A3		0.10	0.50
b	0.17	0.22	0.27
D	0.95	1.00	1.05
D2	0.43	0.48	0.53
E	0.95	1.00	1.05
E2	0.43	0.48	0.53
e		0.65	
L	0.20	0.25	0.30
K	0.15		

Revision History

Revision	Date	Description
0	2022.3.16	Original
1	2022.3.17	Add Notes/Thermal Resistance and make corrections.
1.1	2022.6.10	Modify some errors